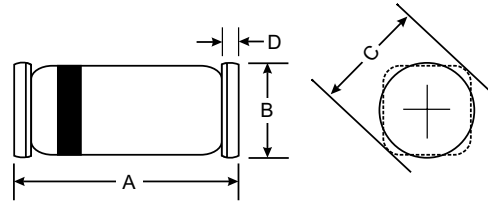


Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance
- Outline Similar to JEDEC 213AA



Mechanical Data

- Case: QuadroMELF, Glass
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Marking: Cathode Band Only
- Weight: 0.034 grams (approx.)

QuadroMELF		
Dim	Min	Max
A	3.3	3.7
B	1.4	1.6
C	1.7Ø Typical	
D	0.3 Typical	
All Dimensions in mm		

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	LS4151	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	75	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	50	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	V
Forward Continuous Current (Note 1)	I_{FM}	300	mA
Average Rectified Output Current (Note 1)	I_O	150	mA
Non-Repetitive Peak Forward Surge Current @ $t = 1.0\mu\text{s}$	I_{FSM}	2.0	A
Power Dissipation	P_d	500	mW
Thermal Resistance Junction to Ambient Air (Note 1)	$R_{\theta JA}$	300	K/W
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +175	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Maximum Forward Voltage	V_{FM}	—	1.0	V	$I_F = 50\text{mA}$
Maximum Peak Reverse Current	I_{RM}	—	50 50	nA μA	$V_R = 50\text{V}$ $V_R = 50\text{V}, T_j = 150^\circ\text{C}$
Junction Capacitance	C_j	—	2.0	pF	$V_R = 0, f = 1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	—	2.0	ns	$I_F = I_R = 10\text{mA}$, $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

Notes: 1. Valid provided that electrodes are kept at ambient temperature.

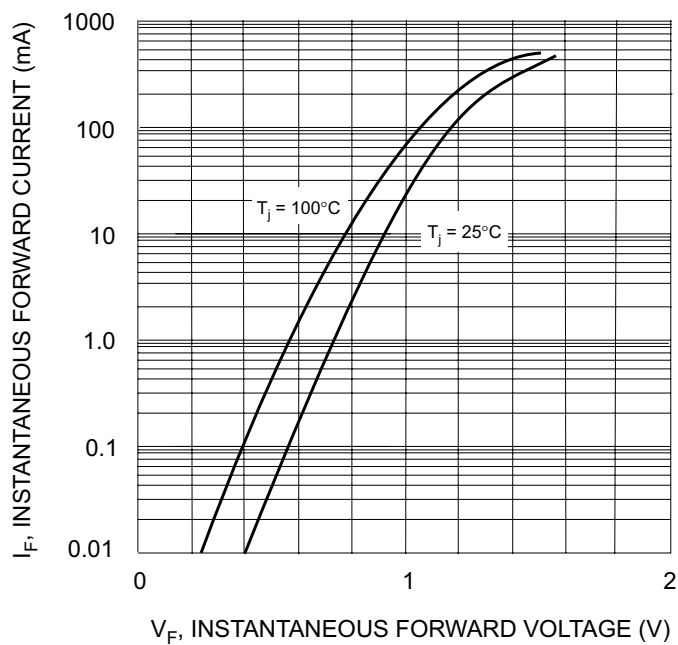


Fig. 1 Forward Characteristics

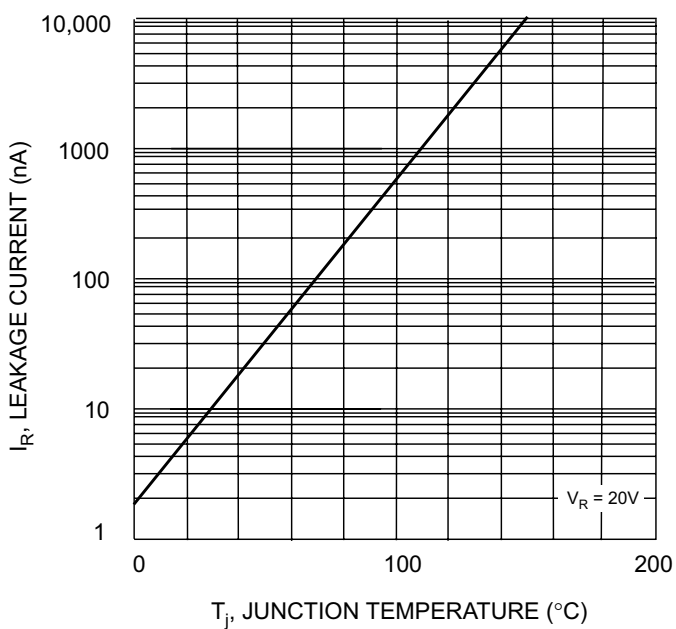


Fig. 2 Leakage Current vs Junction Temperature